

GENERIC PACKAGE VIEW

DPW 4

X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

4211218-2/D

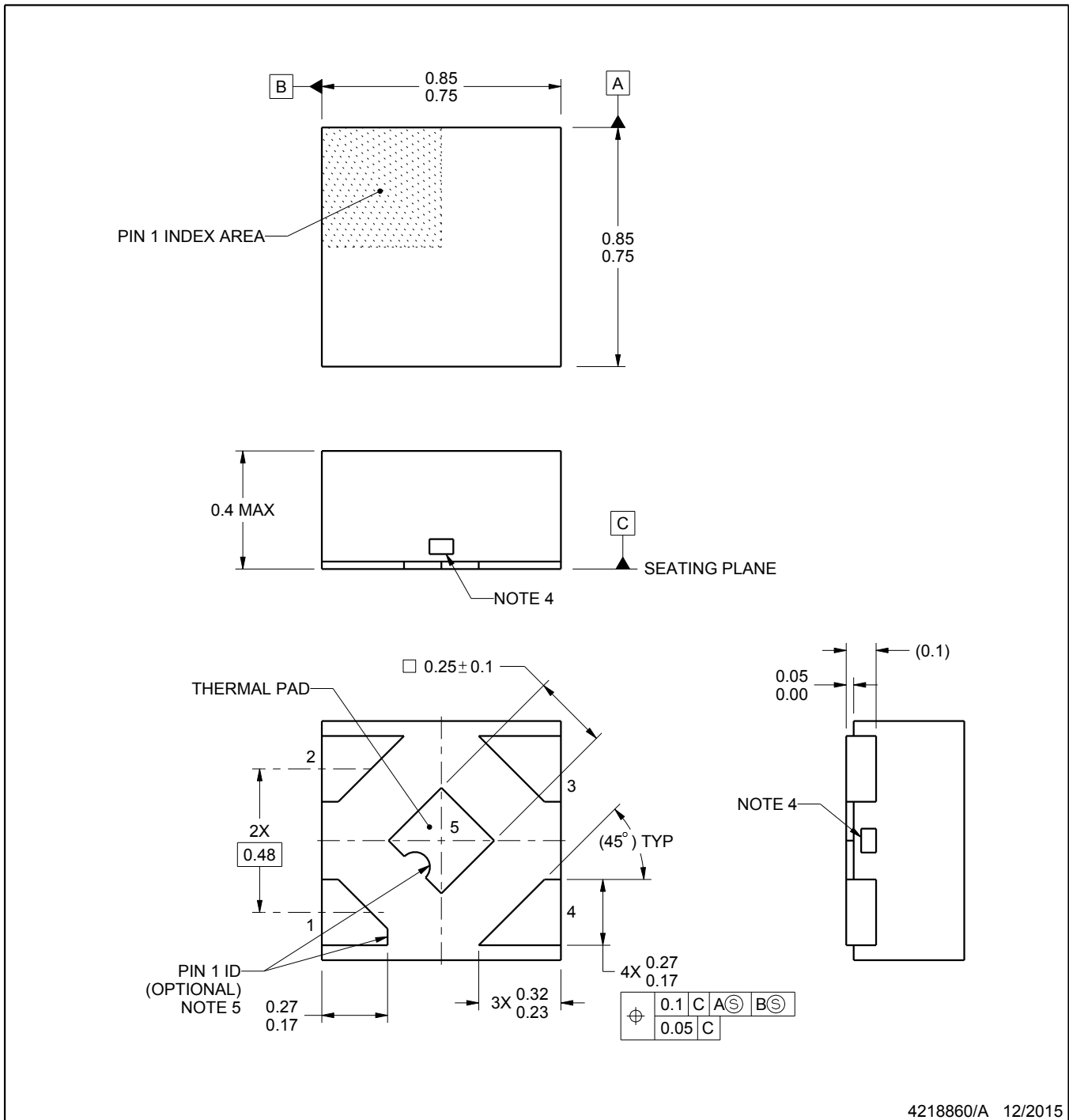


PACKAGE OUTLINE

DPW0004A

X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



4218860/A 12/2015

NOTES:

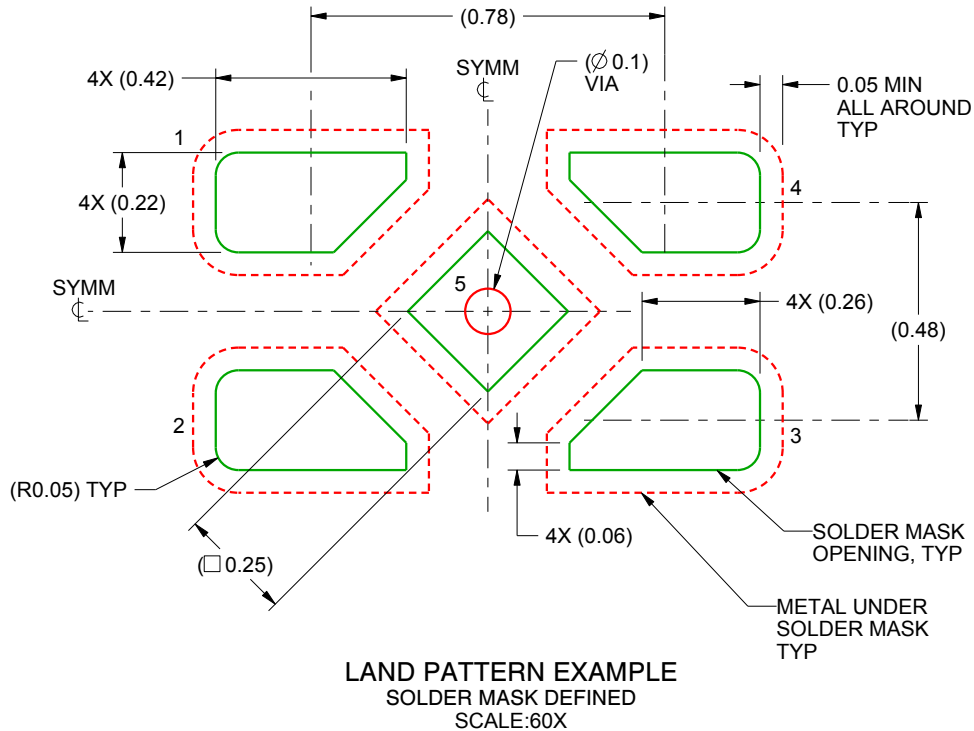
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.
4. The size and shape of this feature may vary.
5. Features may not exist. Recommend use of pin 1 marking on top of package for orientation purposes.

EXAMPLE BOARD LAYOUT

DPW0004A

X2SON - 0.4 mm max height

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4218860/A 12/2015

NOTES: (continued)

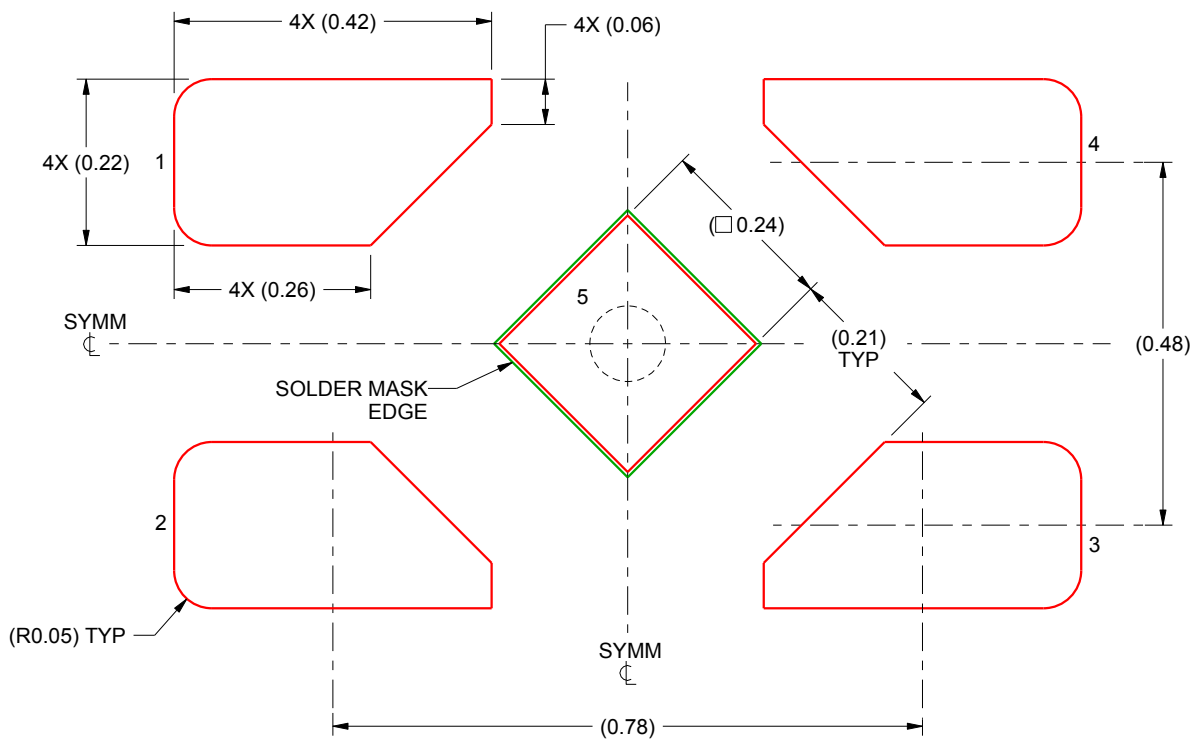
6. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slue271).
7. Vias are optional depending on application, refer to device data sheet. If some or all are implemented, recommended via locations are shown.

EXAMPLE STENCIL DESIGN

DPW0004A

X2SON - 0.4 mm max height

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SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL

EXPOSED PAD 5:
92% PRINTED SOLDER COVERAGE BY AREA
SCALE:100X

4218860/A 12/2015

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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